

Cinterion Wireless Modules

China Electronic Information Product Pollution Act: Marking Information as of January 25, 2007

Chinese Act of February 28, 2006:			X = concentration above maximum concentration values as defined per SJ-T11363-2006 O = concentration below maximum concentration values as defined per SJ-T11363-2006										
EU and China requirements for Maximum Concentration Levels (MCV) based on homogeneous materials for Cd = 0,01wt%, Pb, Hg, Cr6+ and PBB, PBDE = 0,1wt% The Environmental Protection Use Period (EPUP) is 20 years for all wireless modules and terminals. According to the standard for marking, products not separately sold (= components) do not need to be marked, but the customer needs the relevant information for his marking.			EU - RoHS information					China Pollution Act Information					
Product Family	Product Name	Ordering Code	RoHS compatible*)	Additional information	RoHS compatible since date code or Start of production (SOP)	Date code translation (see end of file for details)	Number of RoHS exemption (see end of file for details)	Pb X for C > MCV O for C < MCV 0,1 wt%	Cd X for C > MCV O for C < MCV 0,01 wt%	Hg X for C > MCV O for C < MCV 0,1 wt%	Cr6+ X for C > MCV O for C < MCV 0,1 wt%	PBB X for C > MCV O for C < MCV 0,1 wt%	PBDE X for C > MCV O for C < MCV 0,1 wt%
GSM/GPRS module	AC45	L36880-N8313-A***	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS module	AC65	L36880-N833*-A***	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS/EDGE module	AC75	L36880-N833*-A***	yes		SOP	year and month	7c	X	O	O	O	O	O
HSDPA module	HC15	L30960-N10*0-A100	yes		SOP	year and month	7c	X	O	O	O	O	O
HSDPA module	HC25	L30960-N10*0-A100	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS module	MC39i	L36880-N8532-*100	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS module	MC55	L36880-N837*-100	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS module	MC56	L36880-N837*-100	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS module	MC55i	L30960-N12**-*100	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS/EDGE module	MC75	L36880-N881*-B*00	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM module	TC35i	L36880-N8112-**00	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS module	TC63	L36880-N816*-B***	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS module	TC65	L36880-N835*-B200	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS module	XT55	L36880-N839*-100	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS/EDGE module	XT75	L36880-N883*-A100	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS module	XT65	L36880-N883*-A100	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS Terminal	TC65T	L36880-N8670-B***	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM/GPRS Terminal	MC35iT	L36880-N8665-A100	yes		SOP	year and month	7c	X	O	O	O	O	O
GSM Terminal	TC35i T	L36880-N8615-A100	yes		SOP	year and month	7c	X	O	O	O	O	O

RoHS Exemptions according Annex and latest amendments

Applications of lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) or polybrominated diphenyl ethers (PBDE) which are exempted from the requirements of Article 4(1):

- Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.
- Mercury in straight fluorescent lamps for general purposes not exceeding:
 - halophosphate 10 mg
 - triphosphate with normal lifetime 5 mg
 - triphosphate with long lifetime 8 mg.
- Mercury in straight fluorescent lamps for special purposes.
- Mercury in other lamps not specifically mentioned in this Annex.
- Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
- Lead as an alloying element in steel containing up to 0,35 % lead by weight, aluminum containing up to 0,4 % lead by weight and as a copper alloy containing up to 4 % lead by weight.
- (a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead),
(b) lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications,
(c) lead in electronic ceramic parts (e.g. piezoelectronic devices);
- Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
- Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.

as per 2005/717/EC amending the annex of 2002/95/EC from October 15th, 2005
 9a. DecaBDE in polymeric applications;
 b. Lead in lead-bronze bearing shells and bushes.
 as per 2005/747/EC amending the annex of 2002/95/EC from October 21st, 2005

- Lead used in compliant pin connector systems.
- Lead as a coating material for the thermal conduction module c-ring.
- Lead and cadmium in optical and filter glass.
- Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight.
- Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

more exemptions see 2006/310/EC, 2006/690/EC, 2006/691/EC, 2006/692/EC

Date code

The production date is printed on the device label and is coded as listed in the following table, starting with the character for the production and followed by a number for the month of production if the month is between January and September (1 - 9) or by the characters "O N D" if the month of production is October, November, or December.

M	2000	N	2001	P	2002	R	2003	S	2004	T	2005	U	2006
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Valid examples are "M8" (August 2000), "R2" (February 2003) and "PD" (December 2002).